Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.039”**

**Anode**

**Anode**

**Cathode**

**.039”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .010”**

**Backside Potential: Cathode**

**APPROVED BY: DK DIE SIZE .039” X .039” DATE: 11/9/21**

**MFG: KNOX THICKNESS .008” P/N: 1N5139A-1N5417A**

**DG 10.1.2**

#### Rev B, 7/19/02